

## Abstract

According to this invention, thermal expansion microcapsules can be substantially evenly mixed with a base resin and an expected expansion coefficient for the thermal expansion microcapsules can be obtained during resin molding in a mold. Specifically, this invention provides a method for manufacturing a synthetic resin molding using thermal expansion microcapsules in which the thermal expansion microcapsules are mixed with a base resin and the mixture undergoes resin molding in a mold, wherein the thermal expansion microcapsules are granulated with a given binder resin under a temperature condition in which the thermal expansion microcapsules are not thermally expanded; then the mixture is mixed with the base resin; and the mixture undergoes resin molding.